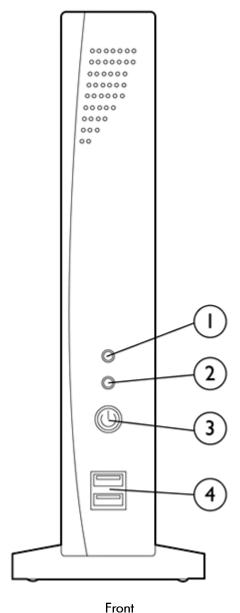
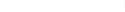
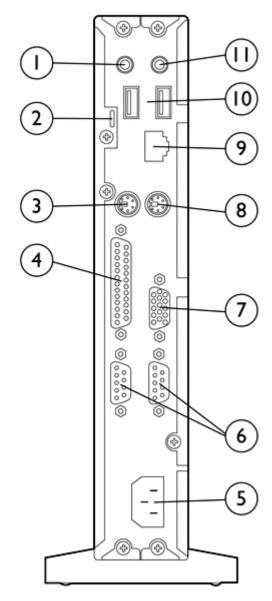
Overview





- Power indicator
- Network activity indicator
- Power switch
- USB 2.0 connectors (two)



Back

- 1. Audio in jack (microphone)
- 2. Cable lock slot
- 3. Keyboard connector -PS/2
- 4. Parallel connector
- 5. Power cord connector
- 6. Serial connectors (two)
- 7. VGA monitor connector
- 8. Mouse connector -PS/2
- 9. RJ-45 10/100 BaseT Ethernet connector
- 10. USB 2.0 connectors (two)
- 11. Audio out jack (speakers, headset)



Overview

At A Glance

- Great combination of performance and small size
- Simplify cable management with an internal power supply
- Via Eden 800 MHz processor
- External (USB) wireless option (a/b/g)
- Includes one parallel, two serial, two PS/2, and four USB 2.0 ports (Front & back panel USB ports for temporary and permanently attached peripherals)
- Available with NeoLinux 3, Windows CE, and Windows XPe
- Management tools provide support for remote configuration, remote shadowing, connection cloning, image cloning, global image updates, scheduled updates, and snap-ins for modular image changes
- HP Neoware e90 is also compatible with HP Neoware Image Manager, providing the ability to stream operating systems and applications on demand, providing all the benefits of thin clients with all the usability and performance of PCs



Standard Features - Models

HP P/Ns	Neoware P/Ns	Model	HP Neoware e90
KF330AA#ABA (NeoLinux	DC-02-GD-AA0	Processor	VIA Eden 800MHz
3) KF330AT#ABA (NeoLinux 3) KF326AA#ABA (CE) KF326AT (CE) KF337AA	(NeoLinux 3) DC-02-GD-AA0 (NeoLinux 3) DC-01-GD-AA0 (CE) DC-01-GD-AA0 (XPe) DC-A3-KD-AA0 (XPe) DC-A3-KE-AA0 (XPe) DC-A3-PE-AA0 (XPe) DC-A3-PE-AA0 (XPe)	Flash	128 MB – 1 GB (Available with no Flash for Neoware Image Manager Models)
(XPe) KF343AA#ABA (XPe) KF351AA#ABA (XPe) KF351AT (XPe)		System Memory	256 MB – 512 MB (DDR2 RAM)
		Operating System	Windows CE Windows XPe Plus Windows XPe NeoLinux 3
		Keyboard	Orders ship with PS/2 US 104 Keyboard
		Mouse	PS/2

^{*}Contact your reseller or HP Direct for other Neoware P/Ns not listed.



Options

Accessories	Mounting Bracket (Wall/Desk) – 10 Pack Mounting Bracket (Wall/Desk) – Single Pack	Part Number AK252AA KL058AA
Wireless Connectivity	USB 802.11a/b/g Wireless Ethernet Adapter (North American Channel Configuration)	AK256AA#ABA
	USB 802.11a/b/g Wireless Ethernet Adapter (European Channel Configuration)	AK257AA
Security	HP/Kensington Cable Lock	PC766A
Memory and Flash	512 MB DDR2 RAM Upgrade	KE678AA
	1 GB DDR2 RAM Upgrade	KE679AA
	512 MB Flash Upgrade XPe	KE706AA
	1 GB Flash Upgrade XPe	KE690AA



Technical Specifications

VIA Eden 800 MHz **Processor** Chipsets CN700 Chipset

128 MB - 1 GB Memory Flash Memory

(Available with no Flash for Neoware Image Manager Models)

System Memory 256 MB - 512 MB (DDR2 RAM)

PS/2

VIA S3 Graphics

> Mode Refresh rate Color depth 8-Bit color 85 Hz Up to 1600 x 1200 16-Bit color 85 Hz Up to 1600 x 1200 32-Bit color 60 Hz Up to 1600 x 1200 85Hz Up to 1280 x 1024

Input/Output/ Keyboard PS/2 US 104 Keyboard Peripheral Support

> Printer Local support in ICA, RDP and local applications (may require additional

> > drivers from manufacturer.)

Video Up to 1600 x 1200 resolution or 32-Bit true color

Wide Screen Monitor Resolutions: (NeoLinux 3 & XPe)

1440x900, 1680x1050 & 1920x1200

Audio Speaker Out - 1/8 inch (3.5 mm) jacks Output

Internal Speaker

Security (hardware) Slot for Kensington Cable Lock

Mouse

ActivIdentity USB Smart Card Reader, vendor models GBURR200 & GBUR300P025

GemAlto Smart Cards (Windows XPe models only)

BioPassword (Special XPe Snap-in)

Server-based Computing

Protocols

RDP (CE & XPe Only) / RDesktop (NeoLinux)

X.11/XDM * (NeoLinux 3 Only)

HP Neoware TeemTalk Terminal Emulator

Networking **Autosensing**

10/100 Ethernet

RJ-45

WakeOnLAN

PXE boot

USB /external wireless option (a/b/g)

I/O Ports and Connectors

2 – Serial Port – D-Sub 9-Pin – Male Connector

1 - Parallel Port - D-Sub 25-Pin - Female Connector

4 (2 front, 2 back) – USB Ports – Type A 2.0

2 – PS/2 Ports (1 keyboard, 1 mouse)

Resident Operating

System

Windows CE

Windows XPe & XPe Plus

NeoLinux 3

Server OS Compatibility /

Support

Citrix Presentation Server 4.0 including the Desktop Broker feature

Citrix Metaframe Presentation Server 3.0

Citrix Metaframe XP Presentation Server

Citrix Metaframe 1.x

Windows 2000/2003 Server Terminal Services



Technical Specifications

- Windows 2000 Advance Server Terminal Services
- Windows NT 4.0 Terminal Server Edition
- VMware Virtual Desktop Infrastructure using RDP
- Linux Terminal Server Project (LTSP) *
- Most mainframes and midrange servers **
- * Requires bios change to PXE boot
- ** Requires TeemTalk (standard on most HP Neoware thin clients)

Local software overview	· · · · · · · · · · · · · · · · · · ·	Windows CE	NeoLinux 3	Windows XPe		
	Citrix ICA	•	•	•		
	RDP	•	•	•		
	Basic Internet Explorer	•				
	Full-function Internet Explorer	From server	From server	•		
	Firefox		•			
	TeemTalk Emulation - 30+	•	•	•		
	X Windows (X11R6 / XDM)	From server	•	From server		
	Acrobat Reader	From server	Snap-in (Add on)	•		
	Windows Media Player	Snap-in (Add on)	From server	•		
	Java Virtual Machine	From server	•	•		
	PPP/DUN	•				
	RealPlayer	From server	Snap-in (Add on)	Snap-in (Add on)		
	Shockwave	From server	From server	From server		
	ThinPrint	•	Snap-in (Add on)			
	Macromedia Flash	From server	From server	•		
	ELO touchscreen support	•	•	•		
	.NET Framework			.NET Ready		
Management	ezRemote Manager and ezUpdate	•	•	•		
	HP Device Manager	•	•	•		
	Altiris	Snap-in (Add on)	Snap-in (Add on)	Snap-in (Add on)		
Security (software)	Read-only file system	•	•	•		
	Locked down user account and configuration	•	•	•		
	HP Neoware Write Filter, Firewall, Security			•		
	Center					
VDI Support	Leostream		•	•		
	Propero		•	•		
	Provision Networks			•		
	Citrix DDI support		•	•		
Languages	Windows CE: English Windows XPe: English, MUI for: French, German, Italian, Spanish, Danish, Greek Windows XPe Plus: More options available with full XPe operating system. NeoLinux 3: English					
Dimensions (approximate)	1.6 W x 9.3 H x 8.7 D in (4.2 x 23.9 x 22.2 cm	n)				



Technical Specifications

Weight (approximate) 8.5 lbs (3.9 kgs)

Environmental Operating temperature 32-95° F (0-35° C)

range

Humidity 20-80% non-condensing

Power* 100-240 VAC, 50-60 Hz 25 W typically-using an internal power supply

* The actual power consumption at your location could vary and is dependent on many factors including but not limited to software load on the thin client, attached peripherals, and environmental factors.

Regulatory Compliance

Product safety

- UL60950-1, CSA22.2/60950-00, IEC 60950-1:2001, NOM-019-SCFI:1998, EN60950-1:2001, GOST-R, SABS LOA, AS/NZS 60950, CCC: GB4943, JS60950, SS60950
- IN-Process: IRAM/S-Mark, SASO 60950-1:2001
- NOT Compliant for e90 V4 Wireless in Chile, Peru, Venezuela, Croatia, Czech Republic, India, Mauritius, Morocco, Serbia, South Africa, Tunisia, Turkey, Ukraine, Bahrain, Kuwait, Pakistan, Qatar, Saudi Arabia, United Arab Emirates, Australia, China, Hong Kong, Indonesia, Japan, Malaysia, New Zealand, Philippines, Singapore, South Korea, Taiwan and Vietnam.

Ergonomics RF Interference

- FCC Part 15C, I.C.: RS210, EN 300 328, EN 300 328, FCC15.247, COFETEL FCC 15.247, WPE: FCC Part 15.247, ICASA (Part 15.247), SRO 797:2004, QAT29/30/31, C-Tick: EN 300 328, SRRC (EN 300 328), OFTA 1035, POSTEL (EN300 328), TELEC (Article 19/19.2), SIRIM(Part 15.247), NTC (Part 15.247), iDA (TS SRD), NTC (EN300 328)
- IN-Process : CNC-Q2-63.01 (wireless only)
- Initiating request: Anatel: Resolution 305
- NOT Compliant for e90 V4 Wireless in Chile, Peru, Venezuela, Croatia, Czech Republic, India, Mauritius, Morocco, Serbia, South Africa, Tunisia, Turkey, Ukraine, Bahrain, Kuwait, Pakistan, Qatar, Saudi Arabia, United Arab Emirates, Australia, China, Hong Kong, Indonesia, Japan, Malaysia, New Zealand, Philippines, Singapore, South Korea, Taiwan and Vietnam

Warranty

Hardware: 3 year limited warranty Software: 12 months

NOTE: Certain restrictions apply. Consult the HP Customer Support Center for details.

Environment-friendly Products and Approach

RoHS Compliance

Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. From July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption



Technical Specifications

Material Usage

under the EU RoHS Directive).

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at: http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.



Technical Specifications

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Hewlett-Packard Corporate Environmental Information For more information about HP's commitment to the environment:

[link to new HP white paper now in progress]

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www.hp.com/hpinfo/globalcitizenship/environment/

productdesign/ecolabels.html ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/

operations/envmanagement.html

©Copyright 2008 Hewlett-Packard Development Company, L.P.

Microsoft, Windows, and Windows NT are trademarks and/or registered trademarks of Microsoft Corporation in the United States and other countries.

The information contained herein is subject to change without notice and is provided "as is" without warranty of any kind. The warranties for HP products and services are set forth in the express limited warranty statements accompanying such products and services. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

